

### ABSTRACT OF THE INVENTION

A method of passivating an integrated circuit (IC) is provided. An insulating layer is formed onto the IC. An adhesion layer is formed onto a surface of the insulating layer by treating the surface of the insulating layer with a gas. A first 5 passivation layer is formed upon the adhesion layer, the first passivation layer and the gas including at least one common chemical element.

2010-09-22 10:30:24